

DOCKET NO: 251598US0

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF :
YUKIO HOSAKA, ET AL. : EXAMINER: RACHUBA, MAURINA T.
SERIAL NO: 10/820,123 :
FILED: APRIL 8, 2004 : GROUP ART UNIT: 3723
FOR: ABRASIVE PAD, METHOD AND :
METAL MOLD FOR MANUFACTURING
THE SAME, AND SEMICONDUCTOR
WAFER POLISHING METHOD

AMENDMENT

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

SIR:

In response to the Official Action dated October 15, 2007, reconsideration is respectfully requested in the above-identified application in view of the following amendments and remarks:

Amendments to the Claims begin on page 2 of this response.

Support for the Amendments begin on page 7 of this response.

Remarks begin on page 8 of this response.